



US00D604257S

(12) **United States Design Patent**
Inatomi et al.

(10) **Patent No.:** **US D604,257 S**
(45) **Date of Patent:** **** Nov. 17, 2009**

(54) **HEATER FOR SEMICONDUCTOR
MANUFACTURING**

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FOREIGN PATENT DOCUMENTS

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(**) Term: **14 Years**

(57) **CLAIM**

(21) Appl. No.: **29/258,749**

The ornamental design for a heater for semiconductor manufacturing, as shown and described.

(22) Filed: **Apr. 27, 2006**

(30) **Foreign Application Priority Data**

DESCRIPTION

Oct. 27, 2005 (JP) 2005-031458

FIG. 1 is an enlarged front elevation view of a heater for semiconductor manufacturing showing our new design;

(51) **LOC (9) Cl.** **13-03**

FIG. 2 is an enlarged left side elevation view, the right side being a mirror image thereof;

(52) **U.S. Cl.** **D13/182**

FIG. 3 is a top plan view thereof;

(58) **Field of Classification Search** D13/182;
118/715, 724, 725; 219/390, 520, 523, 530
See application file for complete search history.

FIG. 4 is a bottom plan view thereof;

(56) **References Cited**

FIG. 5 is an enlarged top plan view of the area 5—5 shown in FIG. 3; and,

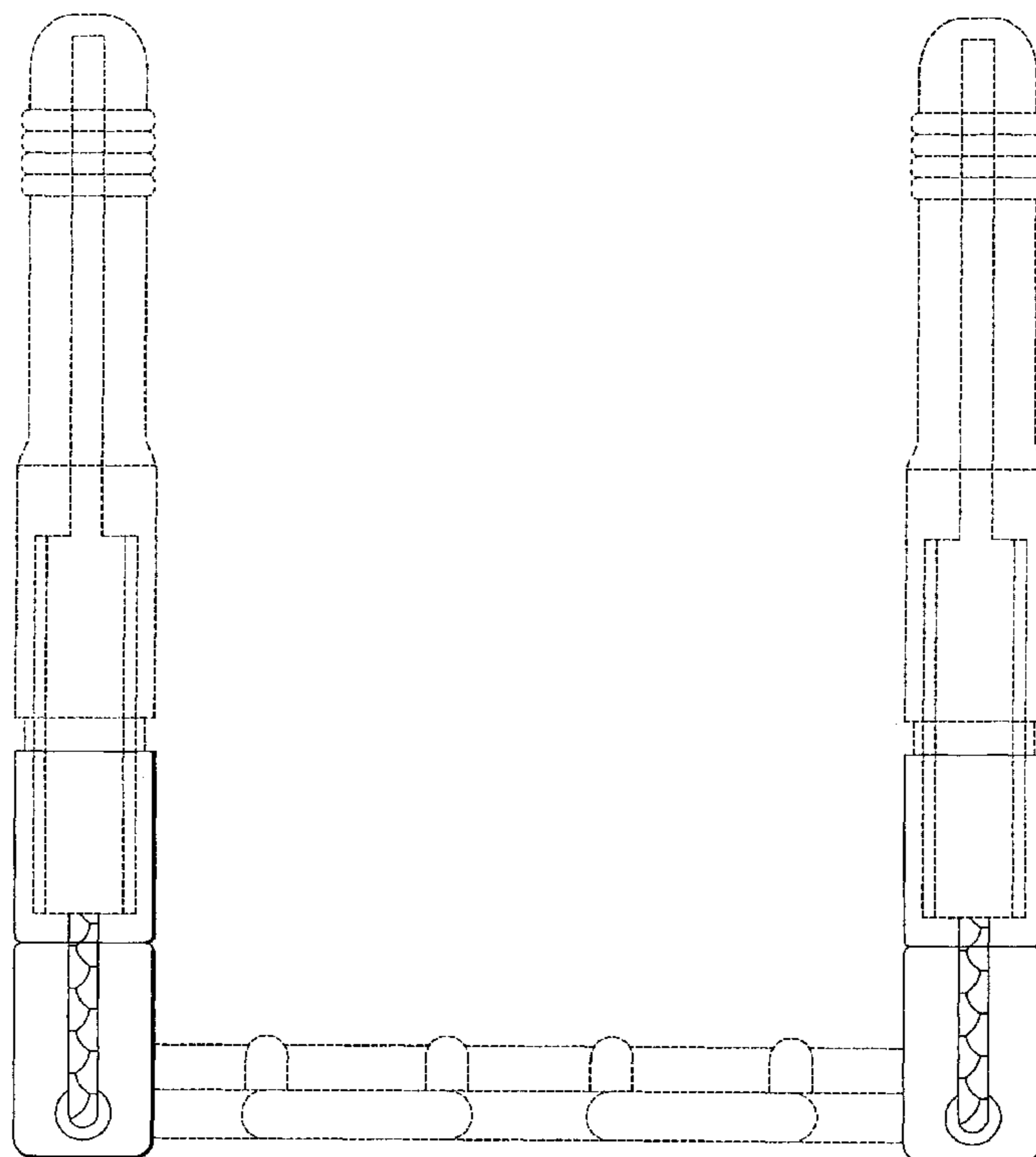
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FIG. 6 is an enlarged bottom plan view of the area 6—6 shown in FIG. 4.

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The broken lines shown in the figures are for illustrative purposes only and form no part of the claimed design.

1 Claim, 5 Drawing Sheets



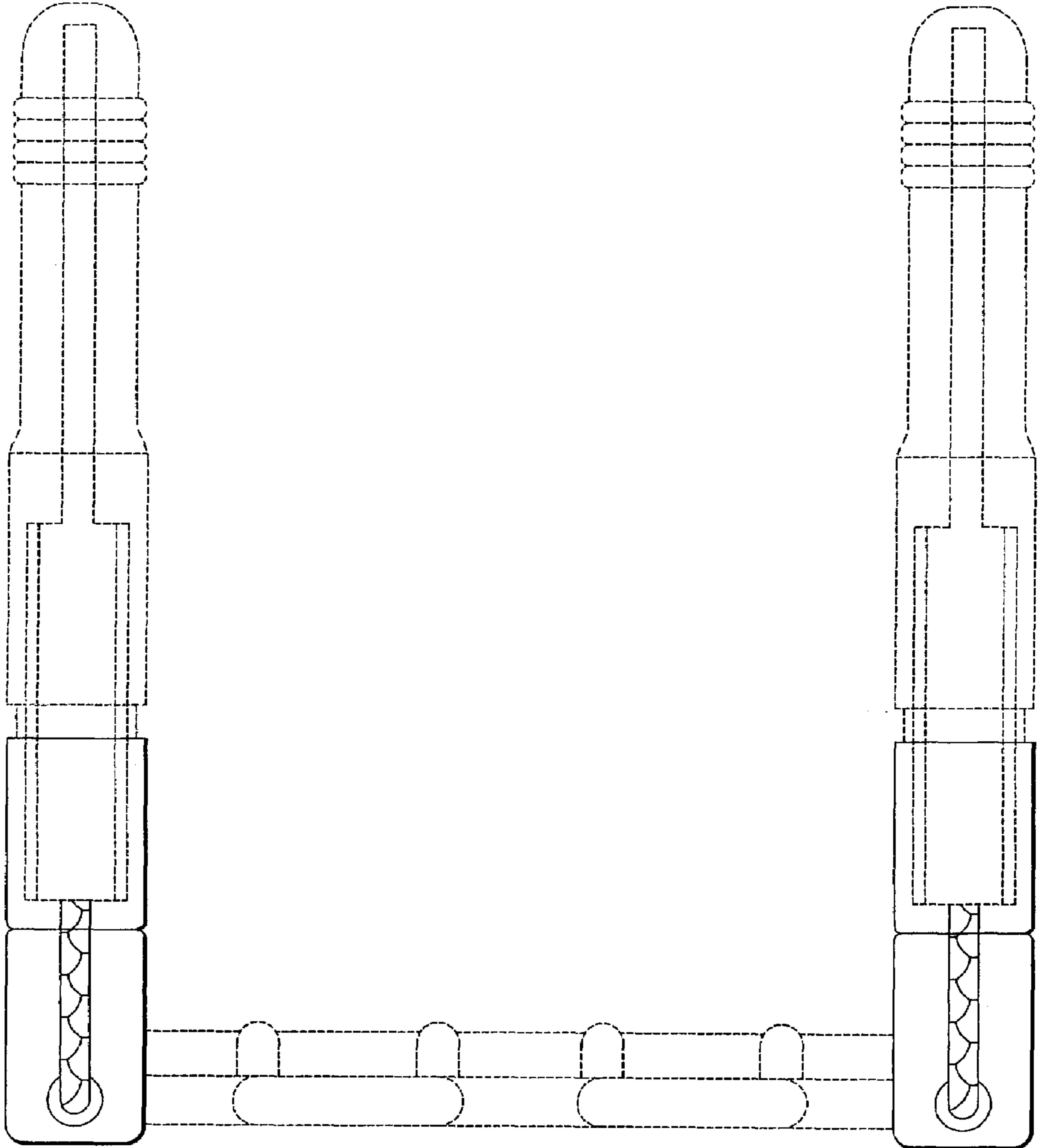


Fig. 1

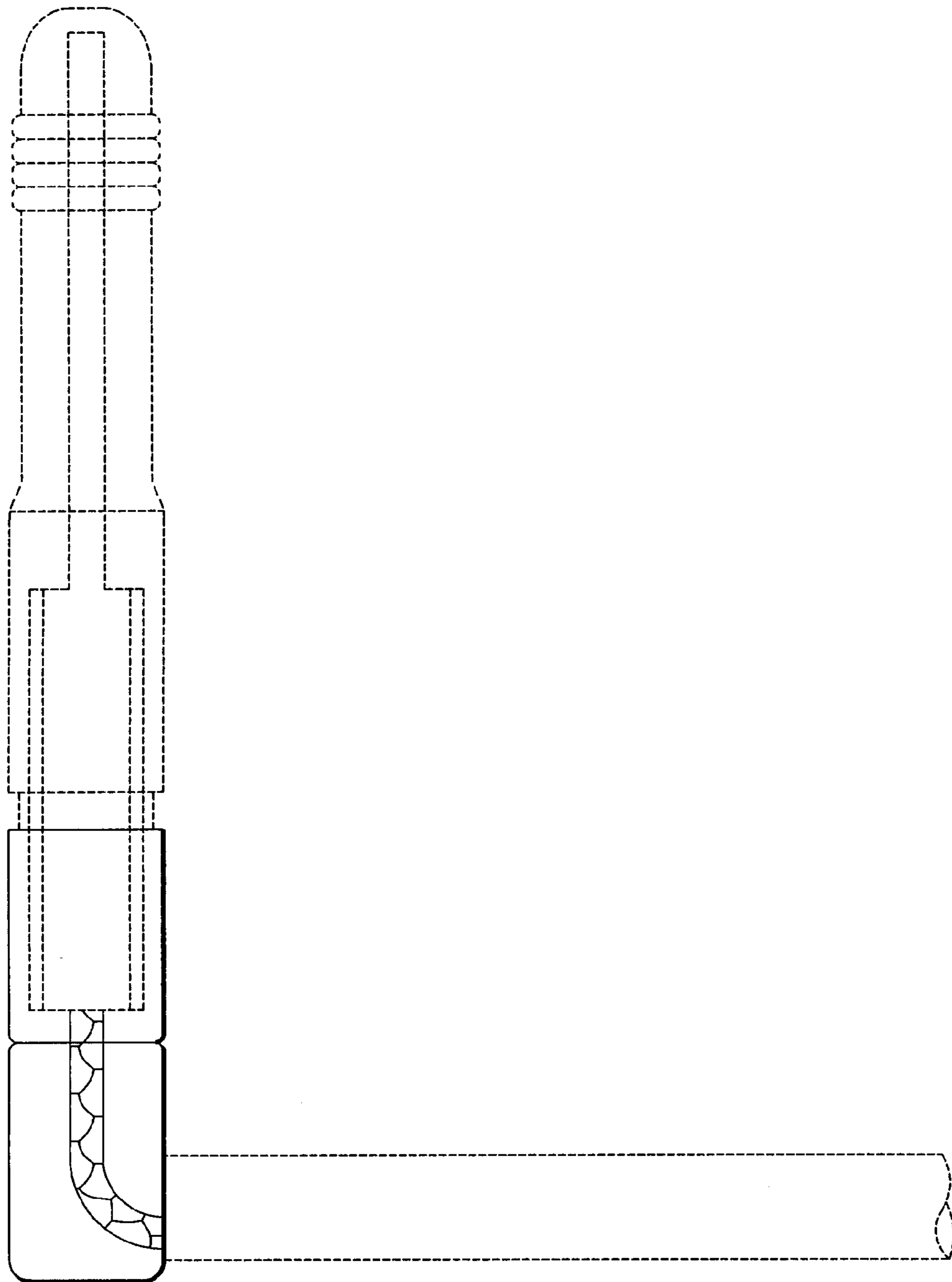


Fig. 2

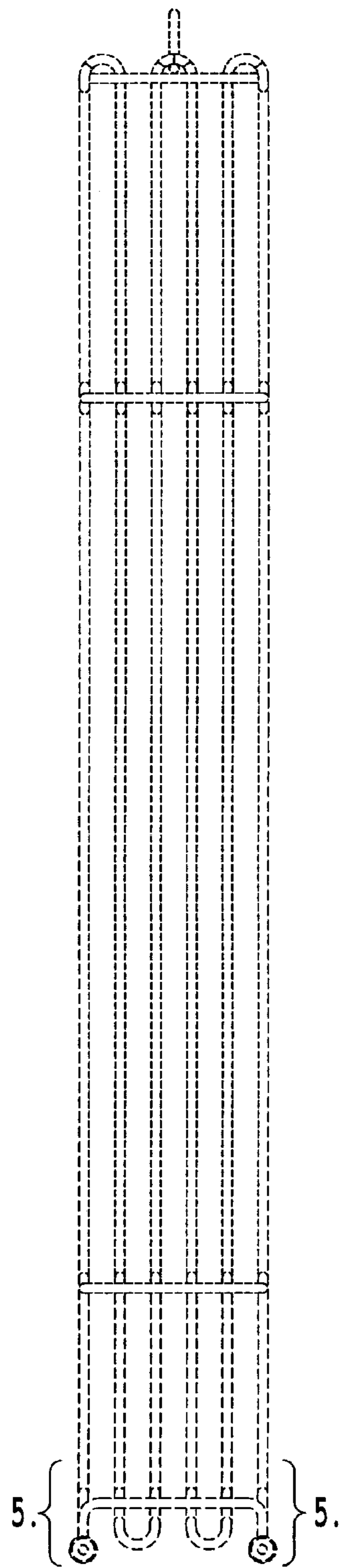


Fig. 3

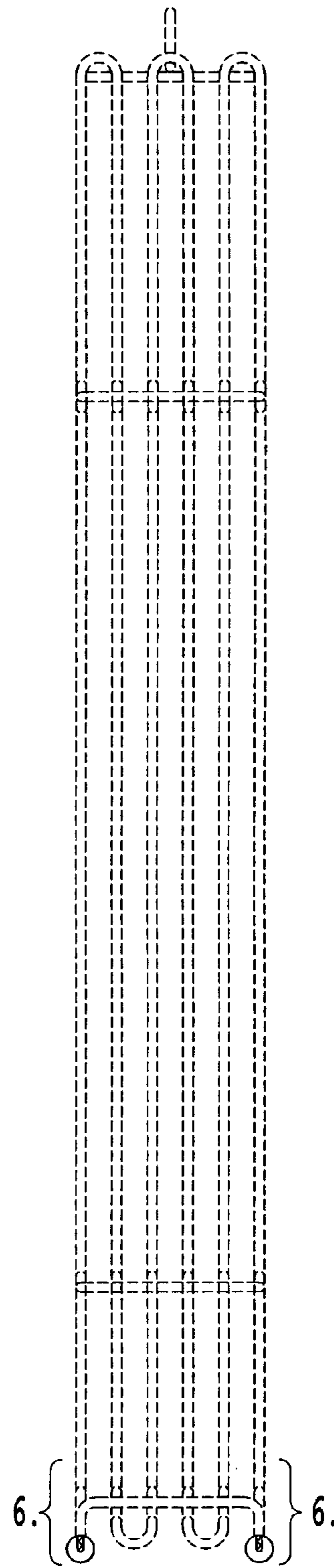


Fig. 4

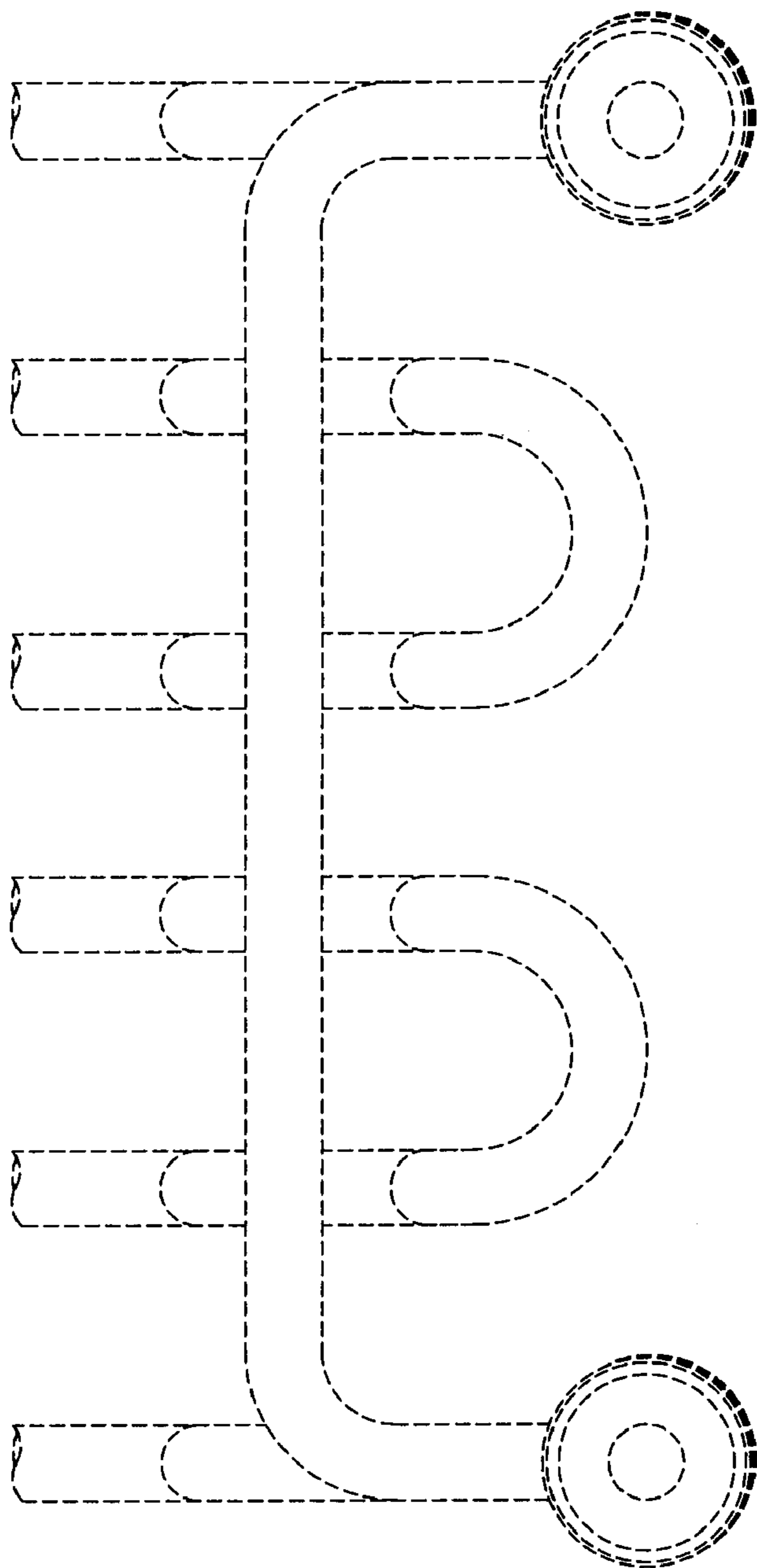


Fig. 5

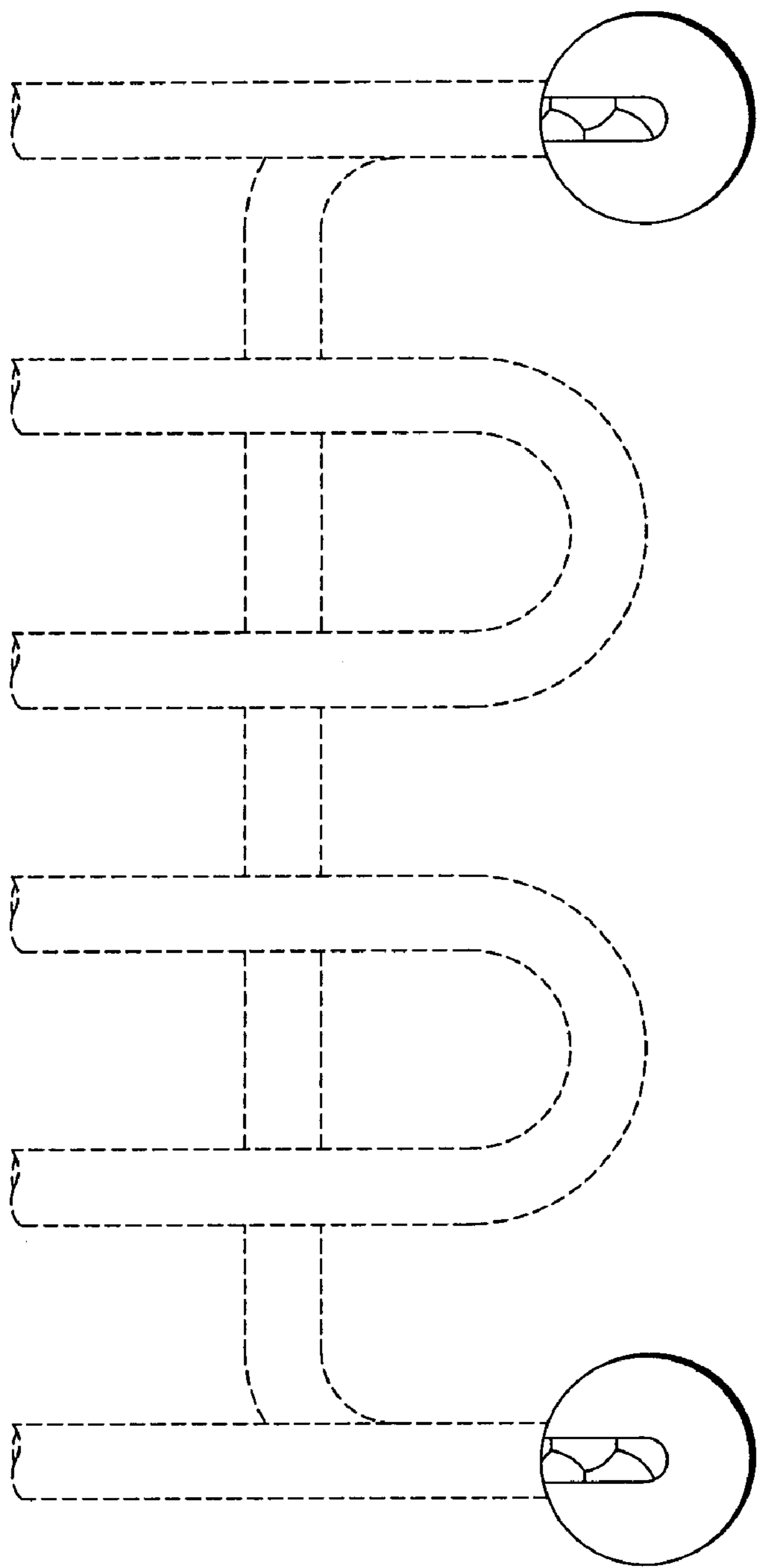


Fig. 6